

ABSTRACT

The present invention is to provide a curable resin composition comprising (I) a reactive silicon group-containing polyoxyalkylenepolymer wherein a introduction rate of a reactive silicon group into molecular chain terminus is not less than 85% as analyzed by ¹H-NMR spectrometry and (II) an epoxy resin. The curable resin obtained from this composition reflects improvements in tensile strength and tensile shear bond strength and in adhesion to various substrates.